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(54) Title: METHOD AND APPARATUS FOR LAMINATING BOARDS		
(57) Abstract A method for laminating boards includes placing boards (10) with a narrow gap (H) therebetween, inserting an adhesive injection nozzle (32) into the gap, discharging adhesive (40) from the nozzle into the gap so that the discharged adhesive makes into contact with the two boards, continuing discharging the adhesive while the boards are being rotated in a planar direction thereof so that the adhesive is placed in a loop into the gap, retreating the nozzle from the gap, and narrowing the gap between the boards so that the adhesive is spread throughout the gap.		